

### 12500 TI Boulevard, MS 8640, Dallas, Texas 75243

# Notification# 20180501002 Datasheet for DAC7568, DAC8168, DAC8568 Change Notification

**Date:** May 03, 2018

To: TOKYO ELECTRON DEVICE (DSTR) PCN

#### Dear Customer:

This is a notice of change to a product data sheet for a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN www admin team@list.ti.com).

Sincerely,

PCN Team SC Business Services

# 20180501002 Data Sheet Change Notification Attachments

### **Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	<b>CUSTOMER PART NUMBER</b>
DAC7568IAPW	null
DAC7568ICPW	null
DAC7568ICPWR	null
DAC8568IDPW	null
DAC8568IAPW	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20180501002			PCN Date:		May 03, 2018					
Title: Datasheet for	DAC	7568, I	DAC	8168, DAC8	3568						
<b>Customer Contact:</b>	PCN A	PCN Manager Quality Services						Quality Services			
<b>Proposed 1<sup>st</sup> Ship Da</b>	te:	Augus	st 0	3, 2018							
Change Type:											
Assembly Site				Design				Wafer Bump Site			
Assembly Process			$\boxtimes$	□ Data Sheet				Wafer Bump Material			
Assembly Material			Щ	Part number change				Wafer Bump Process			
Mechanical Specifi			Щ	Test Site				Wafer Fab Site			
Packing/Shipping/	Labeli	ing		Test Process				Wafer Fab Materials			
			NI.	Notification Details				Wafer Fab Process			
D 111 COL			NC	tification	ı pei	talis					
<b>Description of Chang</b> Texas Instruments Inco								L:6: L:			
The product datasheet(s) is being updated as summarized below.  TEXAS INSTRUMENTS  DAC7568, DAC8168, DAC8568											
SBAS430F – JANUARY 2009 – REVISED APRIL 2018  Changes from Revision E (January 2014) to Revision F  Page											
Updated data sheet to SD	S stan	dard							1		
									6		
				-					6		
Changed I <sub>DD</sub> Normal mod											
maximum value from 2.0n									7		
The datasheet number	will h	e chan	aina	1							
Device Family					Change From:				Change To:		
	DAC7568, DAC8168, DAC8568			SBAS430E				SBAS430F			
http://www.ti.com/product/DAC7568											
Reason for Change:											
To accurately reflect device characteristics.											
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):											
Electrical specification performance changes as indicated above.											
Changes to product identification resulting from this PCN:											
None.											
Product Affected:											
DAC7568IAPW	DA	AC8168IAP\		PW DAC8		568IAPW		С	AC8568ICPW		
DAC7568IAPWR	D/	AC8168IAP\				3568IAPW			AC8568ICPWR		
DAC7568ICPW	DA	AC8168ICP\				3568IBPW	/	DAC8568IDPW			
DAC7568ICPWR	DA	AC8168ICPV		WR	DAC8568IBPW			DAC8568IDPWR			
For questions regarding this notice, e-mails can be sent to the regional contacts shown Representative.											

Location E-Mail

USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com